



# Sierra Components, Inc.

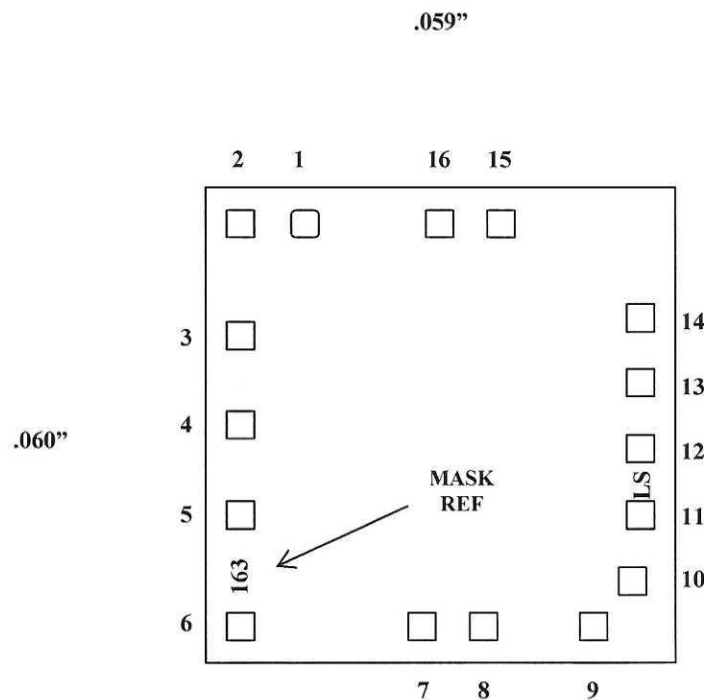
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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTION:**

- 1 CLEAR
- 2 CLOCK
- 3 A
- 4 B
- 5 C
- 6 D
- 7 ENABLE P
- 8 GND
- 9 LOAD
- 10 ENABLE T
- 11 QD
- 12 QC
- 13 QB
- 14 QA
- 15 RIPPLE CARRY OUTPUT
- 16 V<sub>CC</sub>



**Top Material: Al**  
**Backside Material: Si**  
**Bond Pad Size: .004 x .004"**  
**Backside Potential: GND or FLOAT**  
**Mask Ref: 163 LS**

**APPROVED BY: DK**

**DIE SIZE .059" X .060"**

**DATE: 12/22/20**

**MFG: NATIONAL**

**THICKNESS .014"**

**P/N: DM74LS163A**